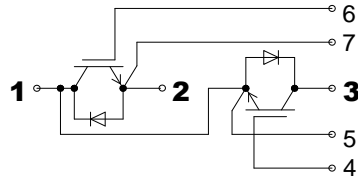


# SGG195T60UC1

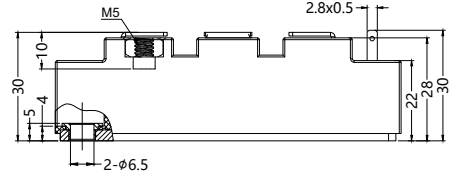
## IGBT Modules



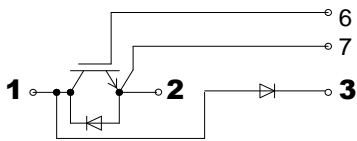
**SGG195T60UC1  
(Half Bridge)**



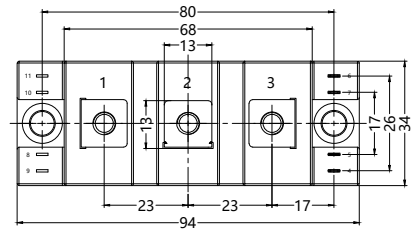
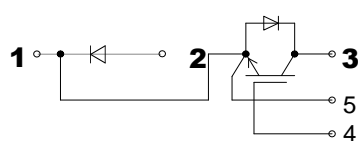
Dimensions in mm (1mm = 0.0394")



**SGD195T60UC1  
(Boost Chopper)**



**SDG195T60UC1  
(Buck Chopper)**



$T_C = 25^{\circ}\text{C}$ , unless otherwise specified

Symbol	Conditions	Values	Units
IGBT			
$V_{CES}$		600	V
$I_C$	$T_C = 25(100)^{\circ}\text{C}$	390(195)	A
$I_{CRM}$	$T_C = 25^{\circ}\text{C}, t_P = 1\text{ms}$	390	A
$V_{GES}$		$\pm 20$	V
$T_{vj}$		$-40 \dots +175$	$^{\circ}\text{C}$
InverseDiode			
$I_F = -I_C$	$T_C = 25(80)^{\circ}\text{C}$	390(195)	A
$I_{FRM}$	$T_C = 25^{\circ}\text{C}, t_P = 1\text{ms}$	390	A
$I_{FSM}$	$t_P = 10\text{ms}; \sin 180^{\circ}; T_j = 25^{\circ}\text{C}$	1450	A
$V_{RRM}$		600	V
Module			
$I_t(\text{RMS})$	$T_{\text{terminal}} = 80^{\circ}\text{C}$	195	A
$T_{\text{stg}}$		$-40 \sim 125$	$^{\circ}\text{C}$
$V_{\text{isol}}$	AC, 1min	4000	V

### Features

- Trench FS IGBT technology
- Low switching losses
- Switching frequency up to 30kHz
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- Soft switching diode Technology
- Package with copper baseplate
- Isolation voltage 4000 V

### Application

- Inverter welding Machines
- UPS
- AC inverter Drives

### Advantages

- space and weight savings
- reduced protection circuits



# SGG195T60UC1

## IGBT Modules

### Characteristics

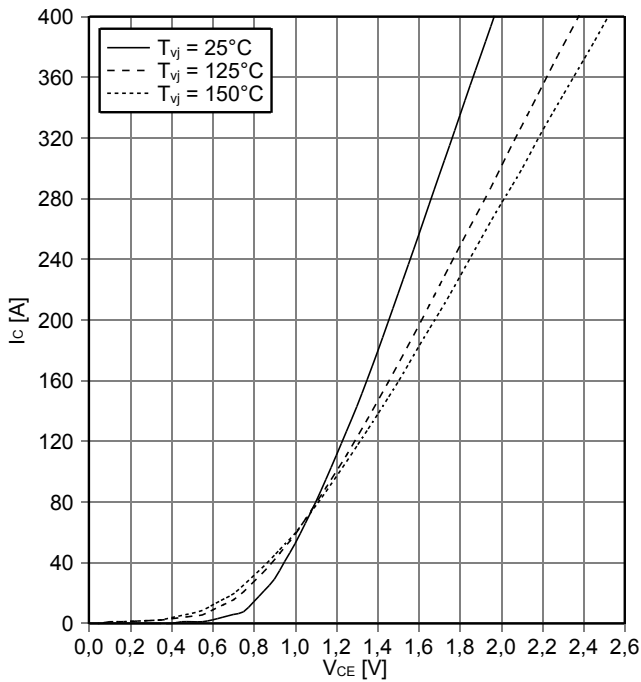
T<sub>c</sub> = 25°C, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V <sub>GE(th)</sub>	V <sub>GE</sub> =V <sub>Ce</sub> , I <sub>c</sub> =3mA	5.0	5.5	6.5	V
I <sub>CES</sub>	V <sub>GE</sub> =0; V <sub>Ce</sub> =V <sub>CES</sub> ; T <sub>j</sub> =25°C			0.40	mA
V <sub>Ce(TO)</sub>	T <sub>j</sub> =25°C		0.9	1.0	V
r <sub>CE</sub>	V <sub>GE</sub> =15V, T <sub>j</sub> =25(150)°C		2.8 (4.3)	4.5(6.0)	mΩ
V <sub>Ce(sat)</sub>	I <sub>c</sub> =195A; V <sub>GE</sub> =15V; chip level		1.65	1.90	V
C <sub>ies</sub>	under following conditions		11.89		nF
C <sub>oes</sub>	V <sub>GE</sub> =0, V <sub>Ce</sub> =25V, f=1MHz		0.70		
C <sub>res</sub>			0.38		
L <sub>CE</sub>				30	nH
R <sub>CC+EE'</sub>	res., terminal-chip T <sub>c</sub> =25(125)°C		0.75(1.02)		mΩ
t <sub>d(on)</sub>	under following conditions: V <sub>CC</sub> =300V, I <sub>c</sub> =195A, R <sub>Gon</sub> =R <sub>Goff</sub> =1Ω, T <sub>j</sub> =150°C V <sub>GE</sub> =±15V		128		ns
t <sub>r</sub>			70		ns
t <sub>d(off)</sub>			505		ns
t <sub>f</sub>			48		ns
E <sub>on</sub> /E <sub>off</sub> /E <sub>ts</sub>			14/7.8/21.8		mJ
Inverse Diode under following conditions:					
V <sub>F</sub> =V <sub>EC</sub>	I <sub>F</sub> =195A; V <sub>GE</sub> =0V; T <sub>j</sub> =25°C		1.55		V
V <sub>(FO)</sub>	T <sub>j</sub> =25(125)°C		0.95(1.05)	1.00(1.20)	V
r <sub>F</sub>	T <sub>j</sub> =25(125)°C		2.2(2.4)	2.5(2.7)	mΩ
I <sub>RM</sub>	I <sub>F</sub> =195A; T <sub>j</sub> =150°C		100		A
Q <sub>rr</sub>	di/dt=2000A/us		30		uC
E <sub>rr</sub>	V <sub>G</sub> =±15V		5.8		mJ
Thermal Characteristics					
R <sub>th(j-c)</sub>	per IGBT			0.22	K/W
R <sub>th(j-c)D</sub>	per Inverse Diode			0.40	K/W
R <sub>th(c-s)</sub>	per module			0.05	K/W
Mechanical Data					
M <sub>s</sub>	to heatsink M6	3		5	Nm
M <sub>t</sub>	to terminals M5	2.5		5	Nm
Weight	typical			155	g

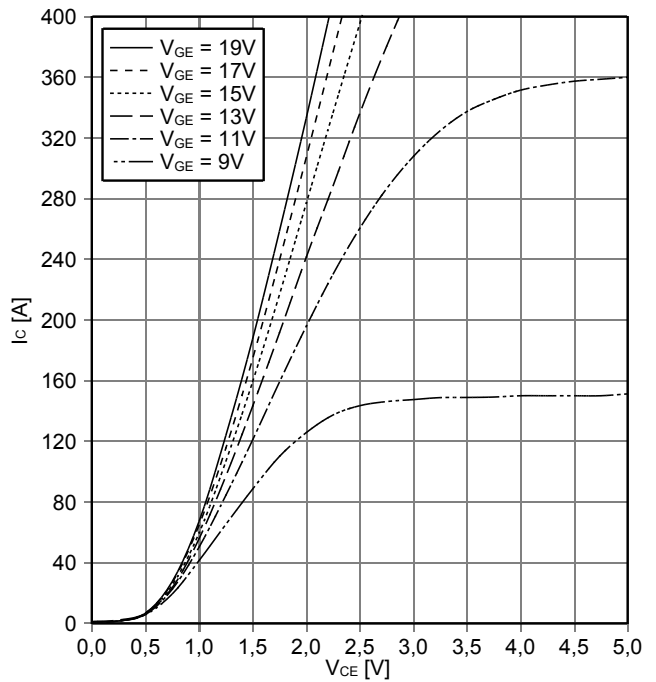
**Sirectifier**<sup>®</sup>

# SGG195T60UC1

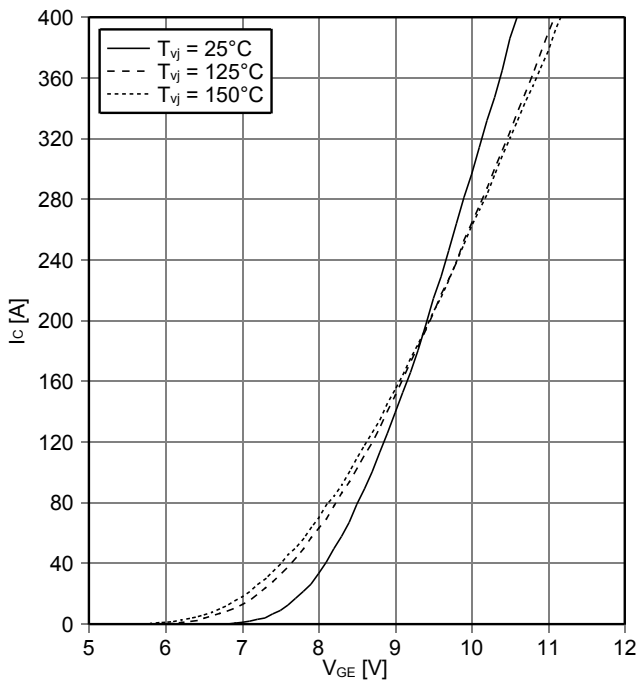
## IGBT Modules



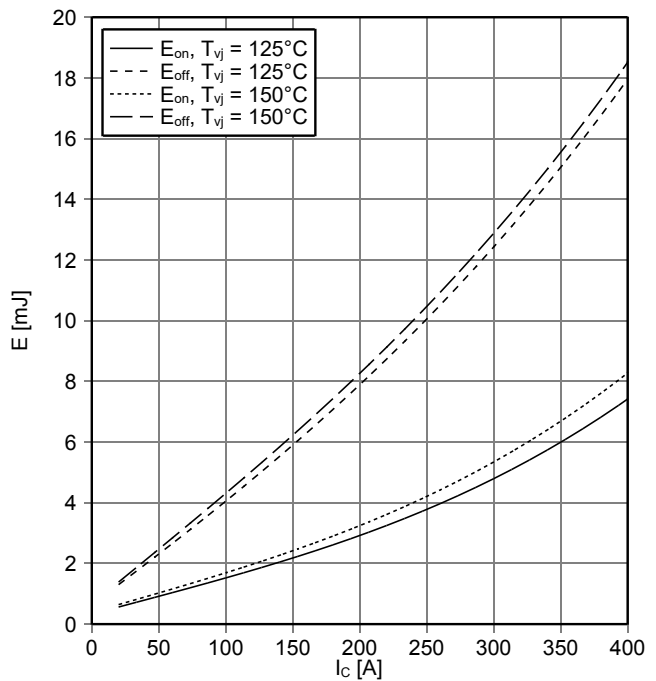
**Fig.1 Output characteristic IGBT, Inverter (typical)**  
 $I_C = f(V_{CE})$   $V_{GE} = 15V$



**Fig.2 Output characteristic IGBT, Inverter (typical)**  
 $I_C = f(V_{CE})$   $T_{vj} = 150^\circ C$



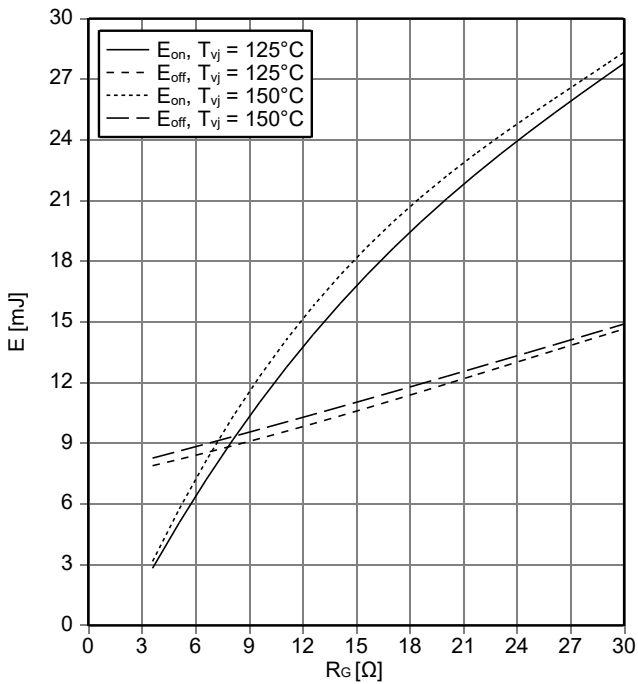
**Fig.3 Transfer characteristic IGBT, Inverter (typical)**  
 $I_C = f(V_{GE})$   $V_{CE} = 20V$



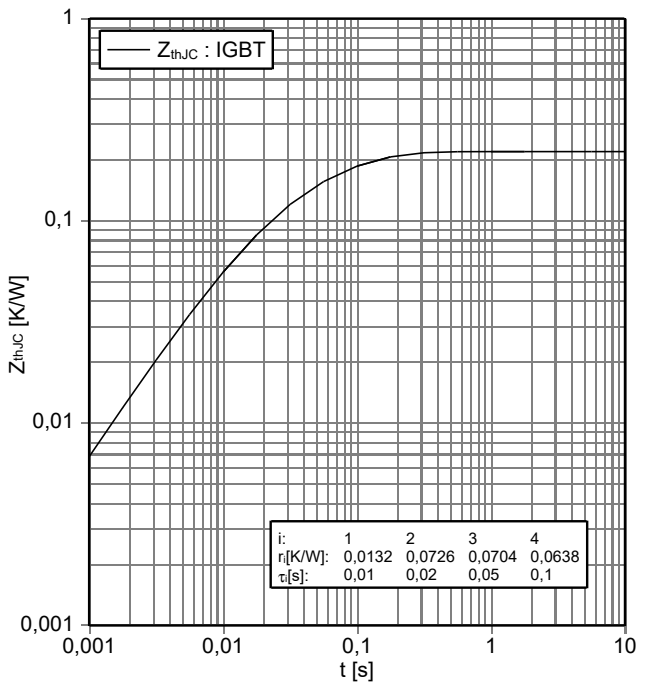
**Fig.4 Switching losses IGBT, Inverter (typical)**  
 $E_{on} = f(I_C), E_{off} = f(I_C), V_{GE} = \pm 15V$

# SGG195T60UC1

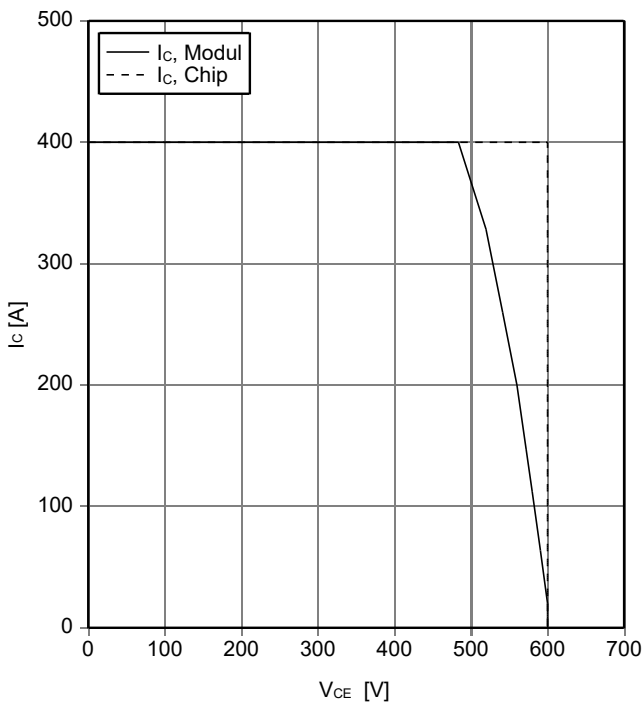
## IGBT Modules



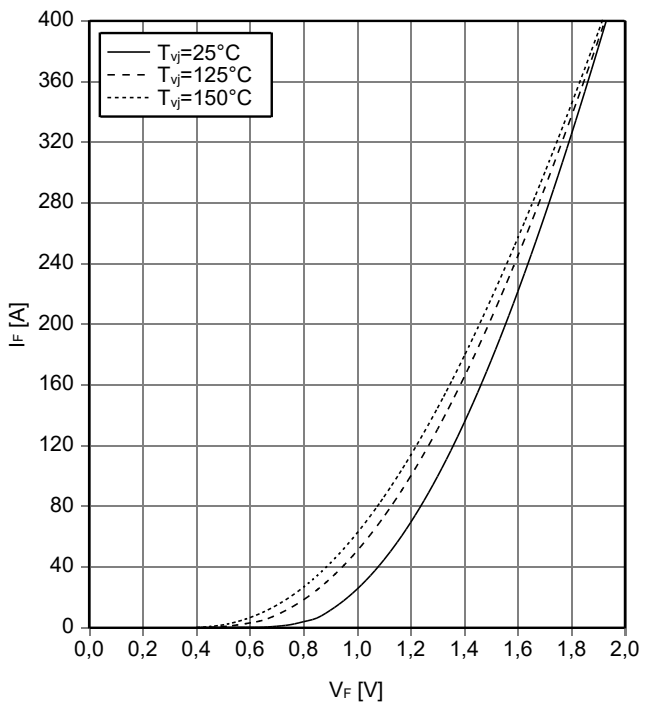
**Fig.5 Switching losses IGBT, Inverter (typical)**  
 $E_{on}=f(R_G), E_{off}=f(R_G), V_{GE} \pm 15V, I_C=200A, V_{CE}=300V$



**Fig.6 Transient thermal impedance IGBT, Inverter**  
 $Z_{thJC}=f(t)$



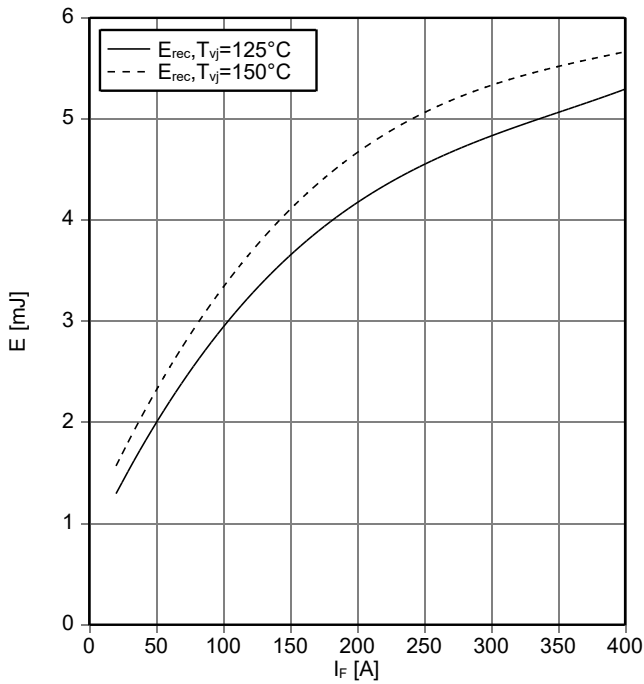
**Fig.7 Reverse bias safe operating area IGBT, Inverter (RBSOA)**  
 $I_C=f(V_{CE}), V_{GE} \pm 15V, R_{Goff}=3.9\Omega, T_{vj}=150^\circ C$



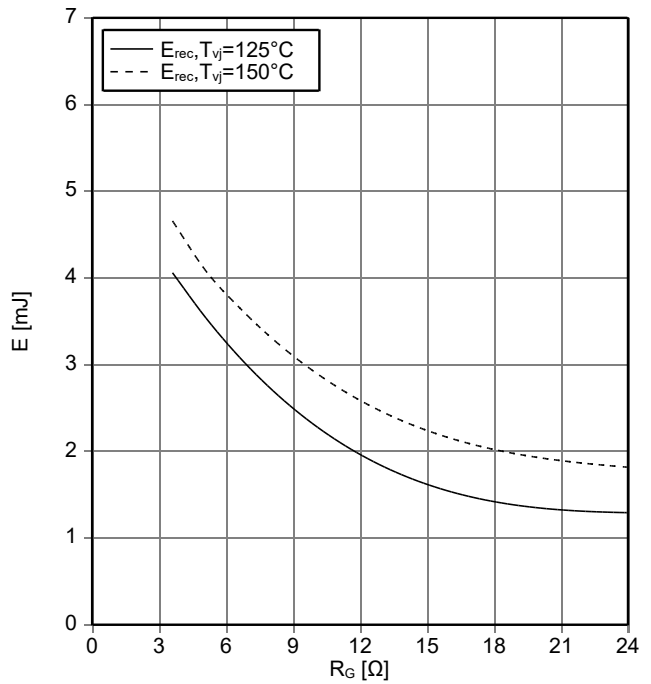
**Fig.8 Forward characteristic of Diode, Inverter (typical)**  
 $I_F=f(V_F)$

# SGG195T60UC1

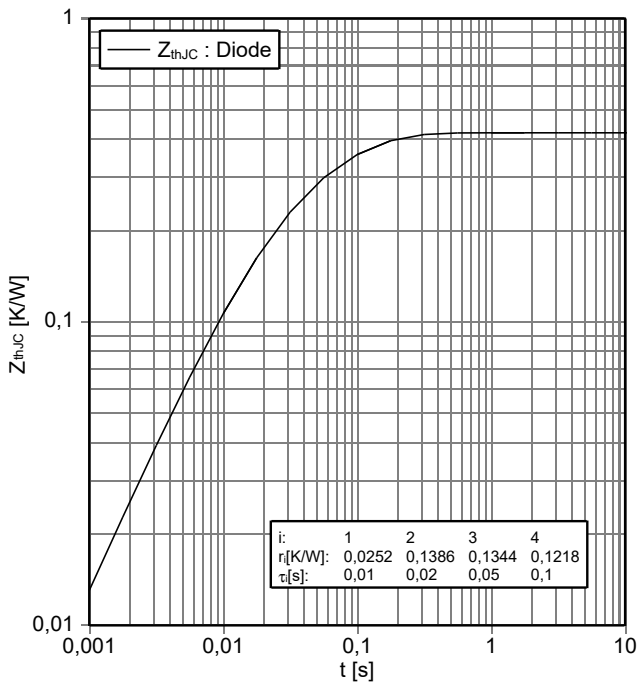
## IGBT Modules



**Fig.9 Switching losses Diode,Inverter(typical)**  
 $E_{rec}=f(I_F), R_{Gon}=3.9\Omega, V_{CE}=300V$



**Fig.10 Switching losses Diode,Inverter(typical)**  
 $E_{rec}=f(R_G), I_F=200A, V_{CE}=300V$



**Fig.11 Transient thermal impedance Diode,Inverter**  
 $Z_{thJC}=f(t)$

